

Standard	Parameter	Specification	Alternative Spec.
2-1.1	Growth Method	CZ	
2-1.3	Crystal Orientation	(100)	(111)
2-1.4, 5	Conductivity Type / Dopant	<i>p</i> / Boron	<i>n</i> / Phosphorus
2-1.8	Wafer Surface Orientation	$0 \pm 1^\circ$	Customization
2-2.1	Resistivity	$1 \sim 100 \Omega \cdot \text{cm}$	Customization
2-6.1	Diameter	$200 \pm 0.2 \text{ mm}$	
2-6.2	Notch Fiducials: Depth, Angle	$1 + 0.25 / - 0 \text{ mm}$, $90 + 5 / - 1^\circ$, r 0.9 mm	
2-6.3	Notch Orientation	$\langle 110 \rangle \pm 1^\circ$	
2-6.6	Edge Profile	T/4	T/3 Template
2-6.7	Thickness	$725 \pm 20 \text{ }\mu\text{m}$	Customization
2-6.8	Total Thickness Variation Max	10 μm	Customization
2-6.9, 10	Bow / Warp Max	65 / 75 μm	Customization
	Surface / Etching Type	Etched / Alkali	Customization
2-8	Appearance	None of Voids, Scratches, Cracks, Stains, Residuals, Saw Mark, Crystalline Defects, Damages.	
	Packing / Separation	Styrofoam Box / Glassine Paper (300 pcs)	